Features

- Trench MOSFET Technology
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free. “Green” Device(Note 1)
- Moisture Sensitivity Level 3

Dual P-Channel Power MOSFET

Maximum Ratings

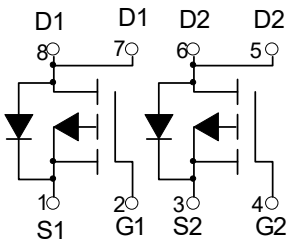
- Operating Junction Temperature Range : -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance: 73°C/W Junction to Ambient(Note 2)

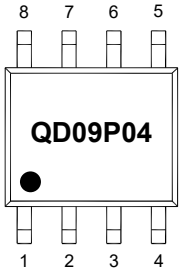
Parameter		Symbol	Rating	Unit
Drain-Source Voltage		V_{DS}	-40	V
Gate-Source Volltage		V_{GS}	±20	V
Continuous Drain Current	T_C=25°C	I_D	-9	A
	T_C=100°C		-5.7	
Pulsed Drain Current(Note3)		I_{DM}	-36	A
Total Power Dissipation(Note4)		P_D	1.7	W
Single Pulsed Avalanche Energy(Note5)		E_{AS}	64	mJ

Note:

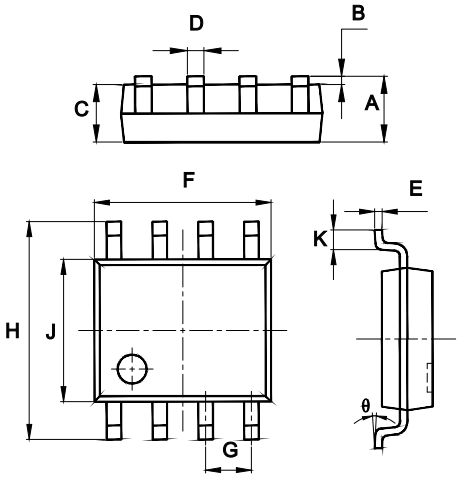
1. Halogen free "Green” products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
2. The value of $R_{\theta JA}$ is measured with the device mounted on $1in^2$ FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C. The Power dissipation P_{DSM} is based on $R_{\theta JA}$ t≤ 10s and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.
3. Pulse Test: Pulse Width≤300us,Duty cycle ≤2%.
4. P_D is based on max. junction temperature, using junction-ambient thermal resistance.
5. T_J=25°C, V_{DD}=-25V,L=0.5mH

Internal Structure and Marking Code



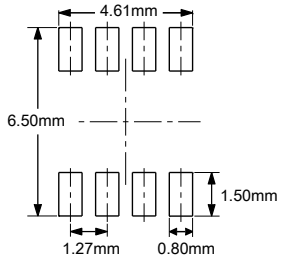


SOP-8



DIMENSIONS					
DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	0.053	0.069	1.35	1.75	
B	0.004	0.010	0.10	0.25	
C	0.053	0.061	1.35	1.55	
D	0.013	0.020	0.33	0.51	
E	0.007	0.010	0.17	0.25	
F	0.185	0.200	4.70	5.10	
G	0.050		1.270		TYP.
H	0.228	0.244	5.80	6.20	
J	0.150	0.157	3.80	4.00	
K	0.016	0.050	0.40	1.27	
θ	0°	8°	0°	8°	

Suggested Solder Pad Layout



Electrical Characteristics @ 25°C (Unless Otherwise Specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS}=0V, I_D=-250μA	-40			V
Gate-Source Leakage Current	I_{GSS}	V_{DS}=0V, V_{GS} =±20V			±100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=-40V, V_{GS}=0V			-1	μA
Gate-Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS}, I_D=-250μA	-1.0	-1.5	-2.5	V
Drain-Source On-Resistance(Note 3)	$R_{DS(on)}$	V_{GS}=-10V, I_D=-9A		17	23	mΩ
		V_{GS}=-4.5V, I_D=-5A		21	28	
Gate Resistance	R_g	F=1 MHz, Open drain		10		Ω
Diode Characteristics						
Continuous Body Diode Current	I_S				-9	A
Diode Forward Voltage	V_{SD}	V_{GS}=0V, I_S=-9A			-1.2	V
Reverse Recovery Time	t_{rr}	I_F=-4A, dI_F/dt=100A/μs		51		ns
Reverse Recovery Charge	Q_{rr}			41		nC
Dynamic Characteristics						
Input Capacitance	C_{iss}	V_{DS}=-30V,V_{GS}=0V,f=1MHz		3302		pF
Output Capacitance	C_{oss}			224		
Reverse Transfer Capacitance	C_{rss}			198		
Total Gate Charge	Q_g	V_{DS}=-20V,V_{GS}=-10V,I_D=-4A		75		nC
Gate-Source Charge	Q_{gs}			8		
Gate-Drain Charge	Q_{gd}			15		
Turn-On Delay Time	$t_{d(on)}$	V_{DD}=-20V, V_{GS}=-10V, R_{GEN}=3Ω, I_{DS}=-4A		7.5		ns
Turn-On Rise Time	t_r			4.2		
Turn-Off Delay Time	$t_{d(off)}$			200		
Turn-Off Fall Time	t_f			70		

Fig. 1 - Typical Output Characteristics

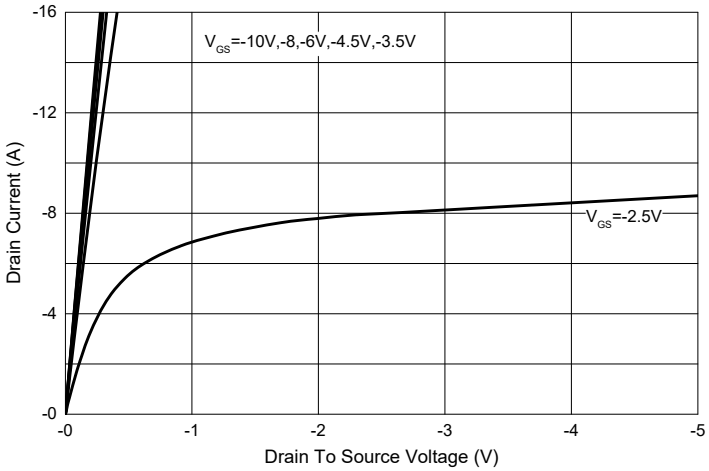


Fig. 2 - Transfer Characteristics

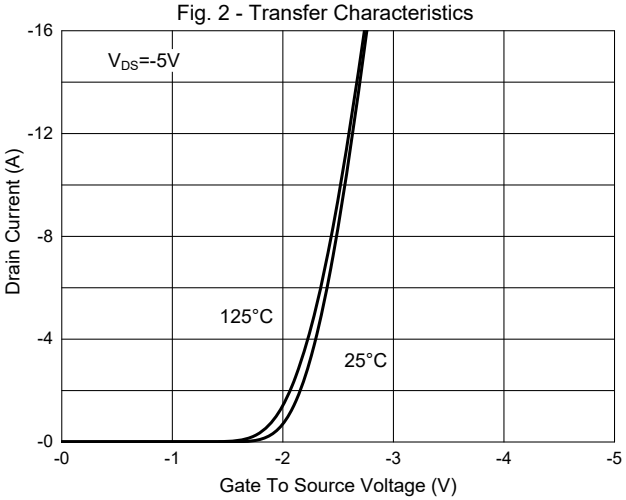


Fig. 3 - $R_{DS(ON)}$—V_{GS}

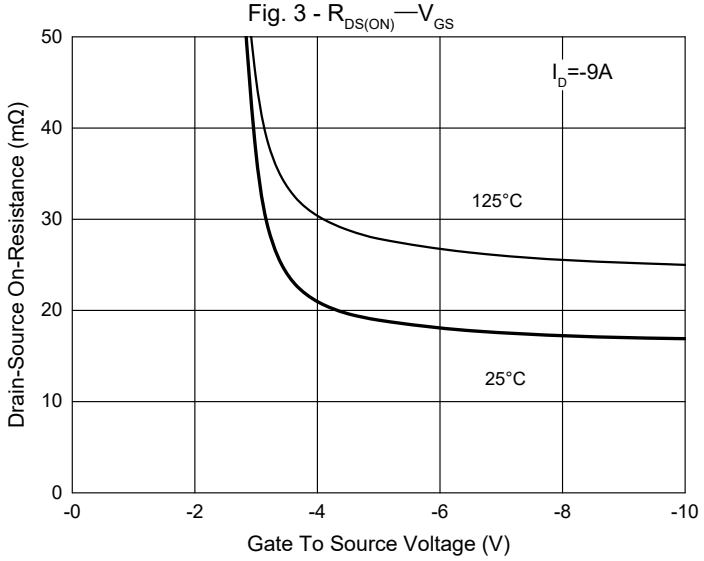


Fig. 4 - $R_{DS(ON)}$—I_D

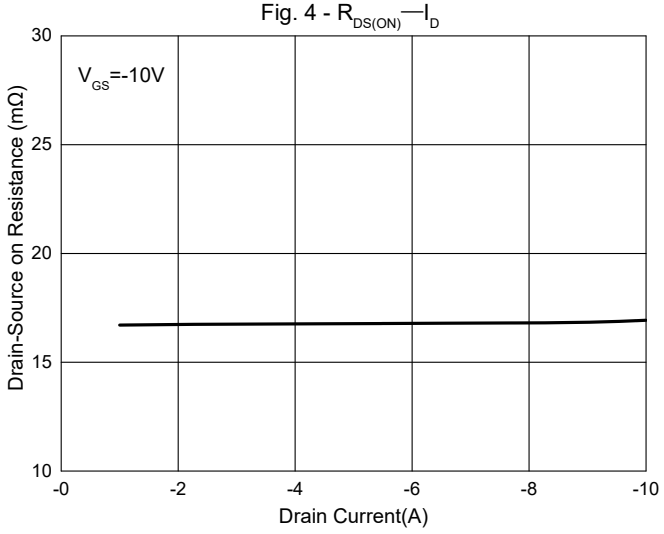


Fig. 5 - Normalized On Resistance Characteristics

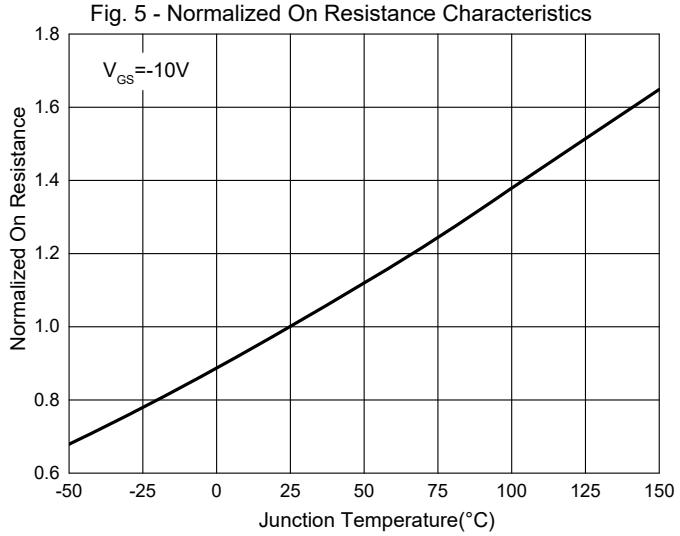


Fig. 6 - Threshold Voltage

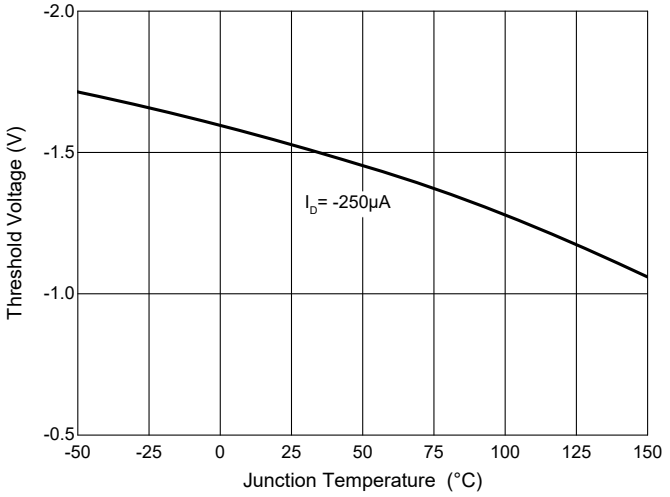


Fig. 7 - Capacitance Characteristics

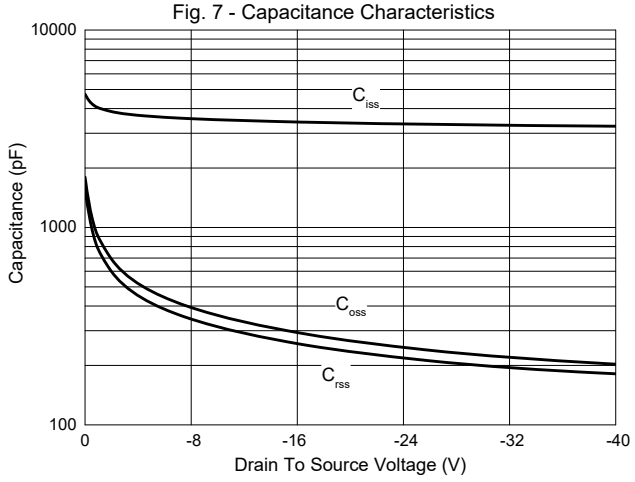


Fig. 8 - Gate Charge

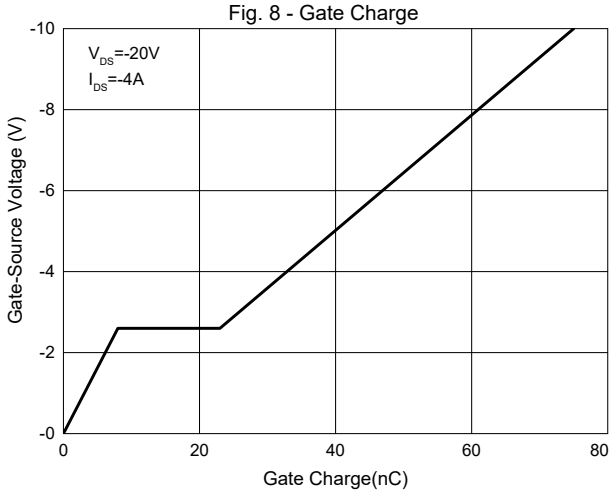


Fig. 9 - I_S—V_{SD}

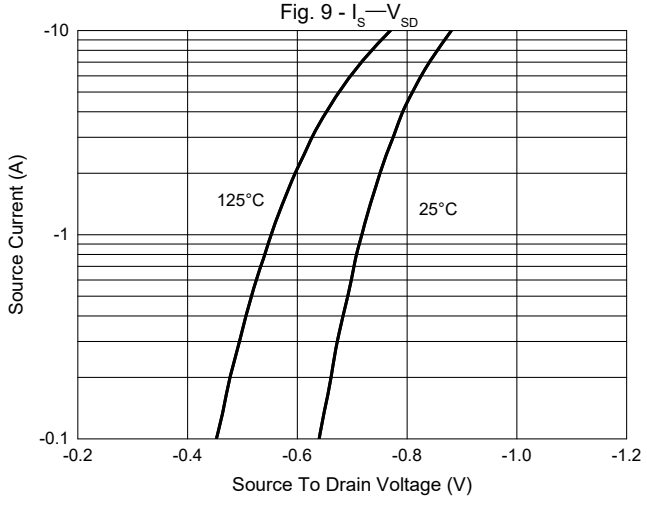


Fig. 10 - ID-TJ

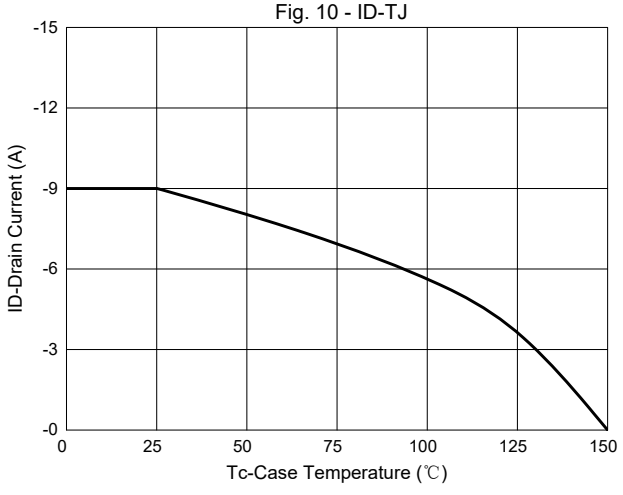


Fig. 11 - PD—TJ

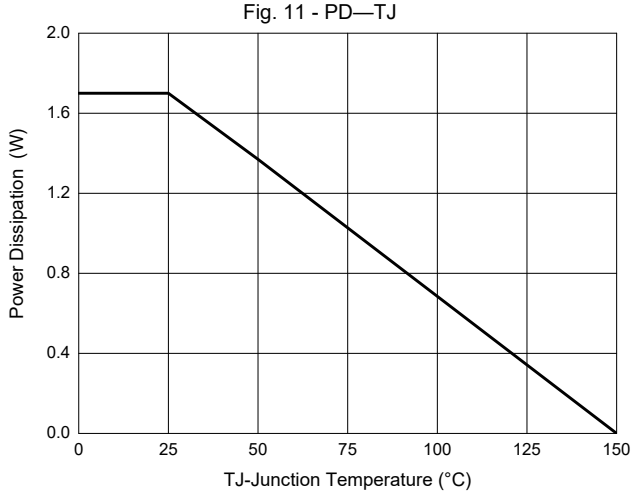


Fig. 12 - Safe Operation Area

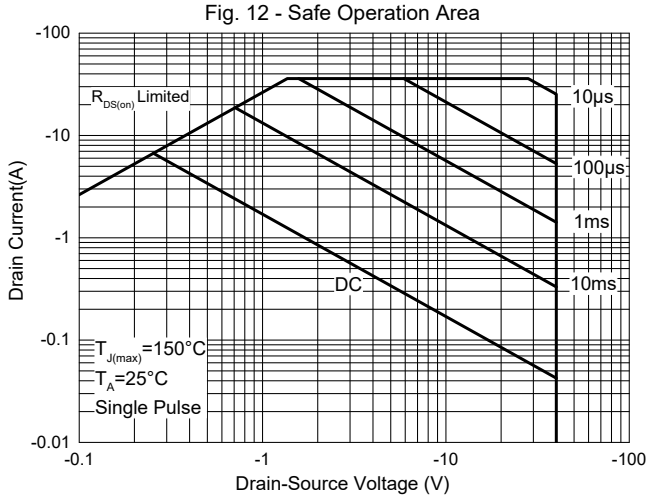
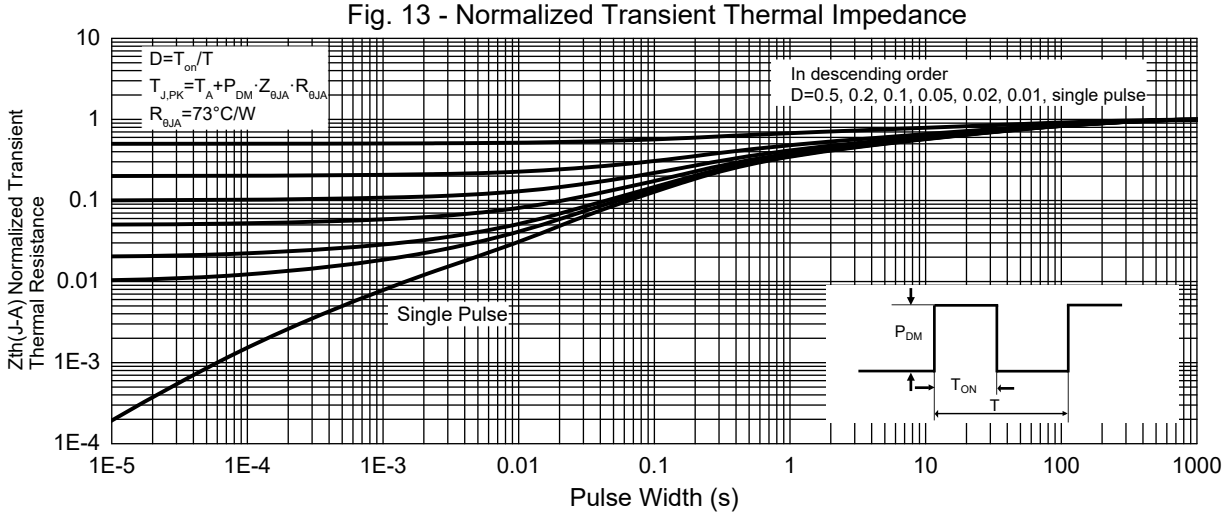


Fig. 13 - Normalized Transient Thermal Impedance



Ordering Information

Device	Packing
Part Number-TP	Tape&Reel: 4Kpcs/Reel